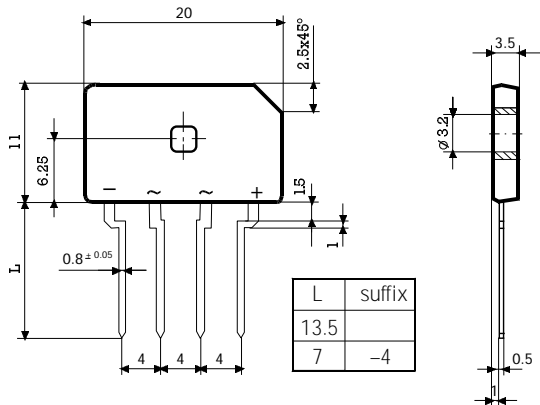



2 Amp. Glass Passivated Bridge Rectifier

| | |
|--|---|
| <p>Dimensions in mm.</p>  <p>Plastic Case</p> <ul style="list-style-type: none"> • Mounting Instructions • High temperature soldering guaranteed: 260 °C – 10 sc. • Recommended mounting torque: 8 Kg.cm. | <p>Voltage 50 to 1000 V.</p> <p>Current 2 A.</p>  <ul style="list-style-type: none"> • Glass Passivated Junction Chips. • UL recognized under component index file number E130180. • Lead and polarity identifications. • Case: Molded Plastic. • Ideal for printed circuit board (P.C.B.). • The plastic material carries U/L recognition 94 V-O. |
|--|---|

Maximum Ratings, according to IEC publication No. 134

| | | FBI2A 4S1 | FBI2B 4S1 | FBI2D 4S1 | FBI2G 4S1 | FBI2J 4S1 | FBI2K 4S1 | FBI2M 4S1 |
|-------------|--|----------------------------------|--------------|--------------|--------------|--------------|--------------|--------------|
| V_{RRM} | Peak recurrent reverse voltage (V) | 50 | 100 | 200 | 400 | 600 | 800 | 1000 |
| V_{RMS} | Maximum RMS voltage (V) | 35 | 70 | 140 | 280 | 420 | 560 | 700 |
| $I_{F(AV)}$ | Max. Average forward current with heatsink without heatsink | 4.5 A at 65 °C 2.0 A at 25 °C | | | | | | |
| I_{FSM} | 8.3 ms. peak forward surge current (Jedec Method) | 60 A | | | | | | |
| I^2t | Rating for fusing ($t < 8.3$ ms.) | 15 A ² sec | | | | | | |
| V_{DIS} | Dielectric strength (terminals to case, AC 1 min.) | 1500 V | | | | | | |
| T_j | Operating temperature range | – 55 to + 150 °C | | | | | | |
| T_{stg} | Storage temperature range | – 55 to +150 °C | | | | | | |

Electrical Characteristics at Tamb = 25°C

| | | |
|---------------|---|-----------|
| V_F | Max. forward voltage drop per element at $I_F = 2$ A | 1.0 V |
| I_R | Max. reverse current per element at V_{RRM} | 5 μ A |
| $R_{th(j-c)}$ | MAXIMUM THERMAL RESISTANCE Junction-Case. With Heatsink. | 12 °C/W |
| $R_{th(j-a)}$ | Junction-Ambient. Without Heatsink. | 40 °C/W |

Characteristic Curves

